

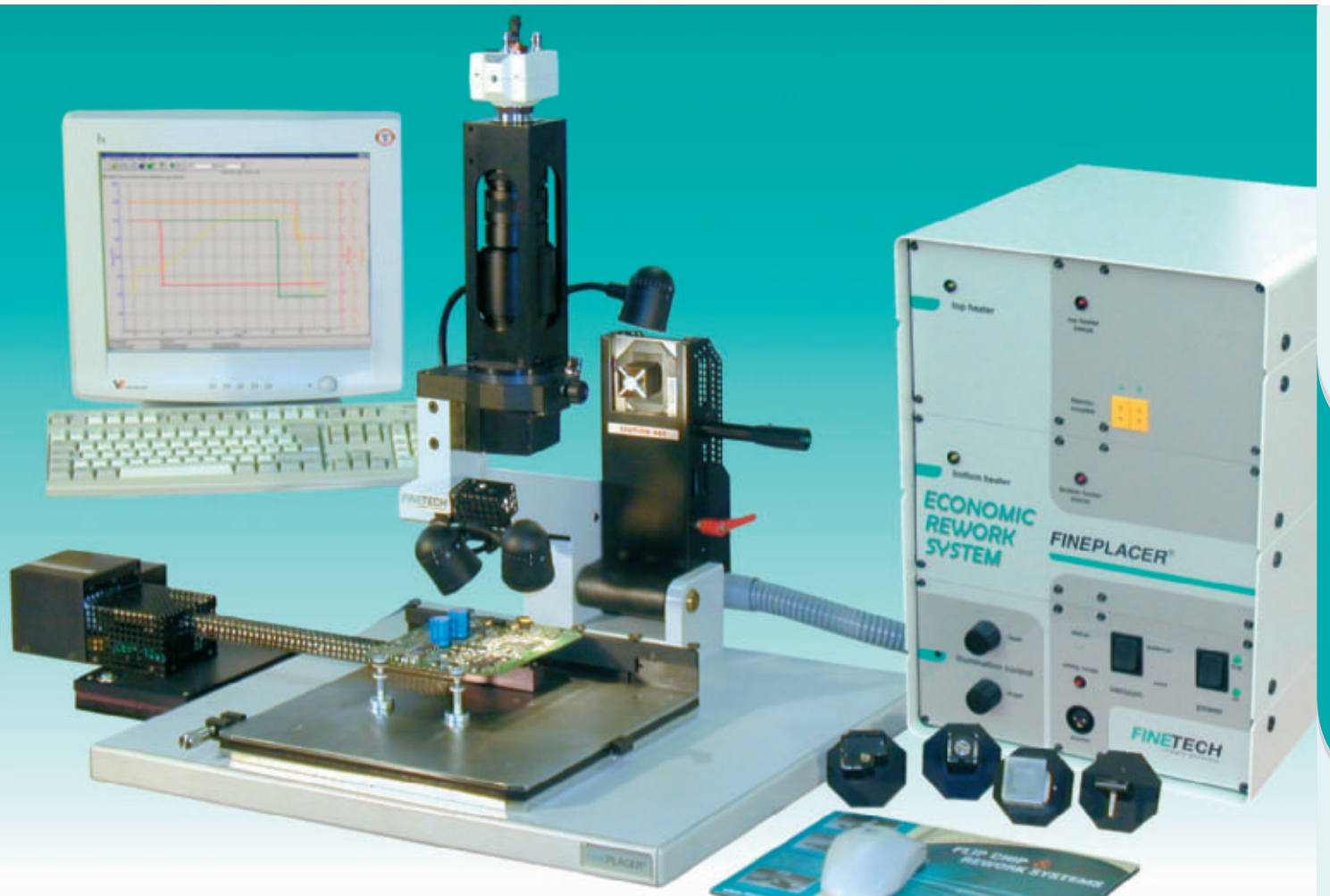
# FINEPLACER® ERS 20

## ECONOMIC REWORK SYSTEM

FINEPLACER® SYSTEM

REWORK

FLIP CHIP



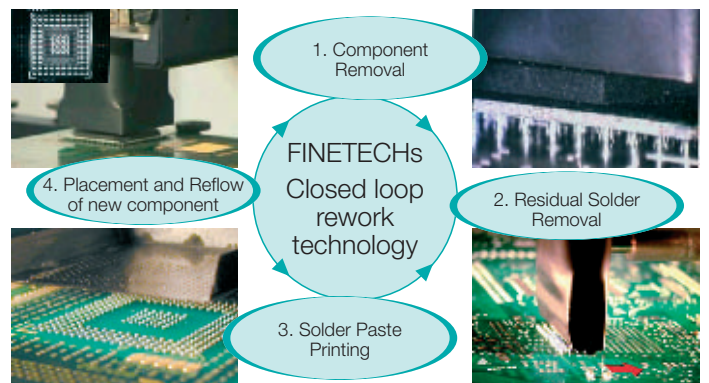
BGA - CGA - CBGA -  $\mu$ BGA - CSP - QFP - TSOP - PLCC - Small Passives - RF · Shields - Connectors ...

### Features

- Placement accuracy 20 microns (<1 mil)
- Patented **V**ision **A**lignment **S**ystem (VAS) with stationary beam splitter
- **C**ontrolled **M**ixed **S**oldering **S**ystem – **C**OMISS
- Windows® based graphic user interface – „WinReflow“
- Reliable rework process
- Compact design
- Quick set up and easy to operate
- Proven FINETECH soldering head technology
- Lead-free compatible rework

### Closed Loop Rework Technology

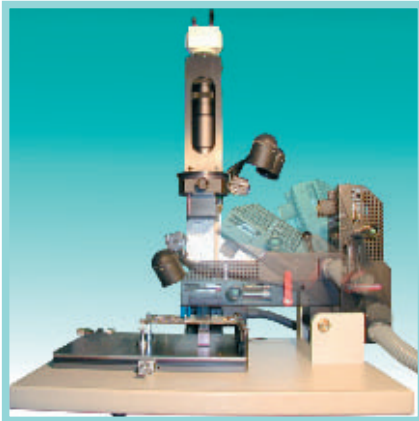
- Component Removal
- Residual Solder Removal
- Solder Paste Printing
- Placement and Reflow of new component



(Opt. BGA, CSP Reballing Module, RC5)

# FINEPLACER<sup>®</sup> ERS 20

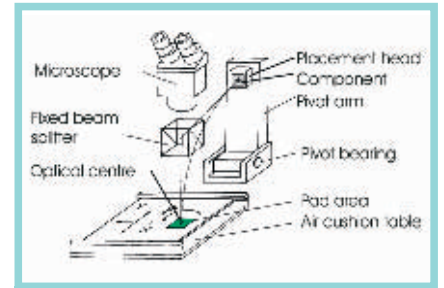
## ECONOMIC REWORK SYSTEM



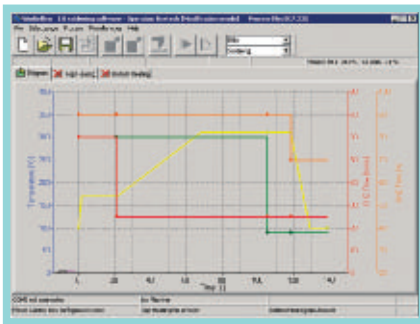
System Side View

### Vision Alignment System

- **P**atented design with stationary beam splitter
- Simultaneous representation of the components contact and substrates pad by means of the beam splitter
- Placement accuracy 20 microns
- Only one moving component – reflow arm
- Very rapid rough and fine positioning by using air cushion table and adjustment screws



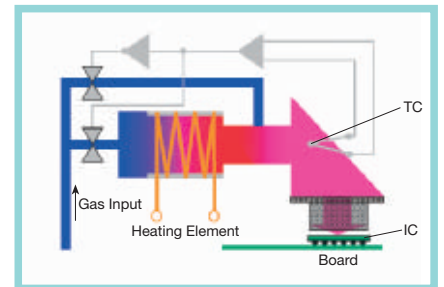
VAS – Working Principle



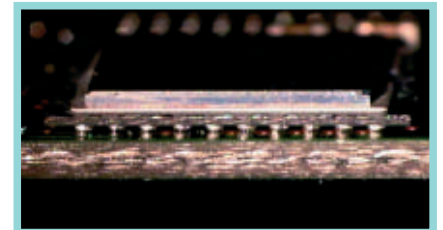
Graphic User Interface

### Process Control

- **C**ontrolled **M**ixed **S**oldering **S**ystem – **C**OMISS
- Windows<sup>®</sup> based graphic user interface
- Micro-controller based real time process control
- Rapid heating and cooling
- Precise temperature and flow control guaranties a reliable rework process
- Low thermal mass nozzles ensure short soldering times and fast temperature ramping



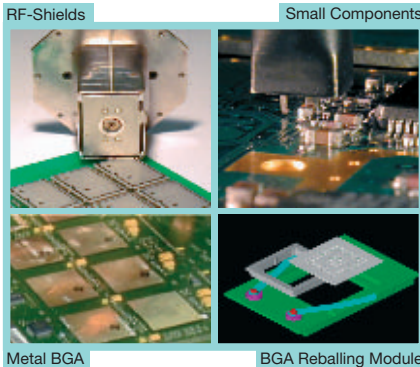
COMISS – Working Principle



Real Time Process Inspection

### Process Observation and Inspection

- Real time process observing and inspection by video system (opt. RW1)

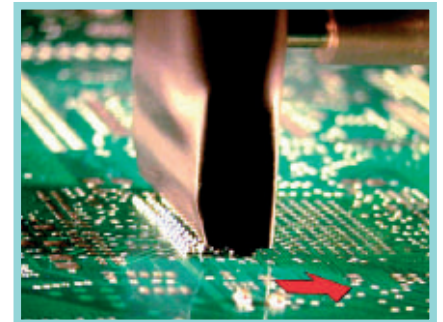


Metal BGA

BGA Reballing Module

### Applications

- BGA, PBGA, CBGA,  $\mu$ BGA, CSP, QFP, TSOP, PLCC, small components as 0201, 0402 (with opt. optics), 0603, connector
- Shielding (single or multiple), Shielding Frame
- C4 Flip Chip rework
- Customized applications



Residual Solder Removal

### Technical Data

<b>Max board size</b>	310 x 460 mm	
<b>Heater</b>	<b>top</b>	<b>bottom</b>
max. temperature	380°C	360°C
max. air flow	70 l/min	160 l/min
<b>Facilities</b>		
Power	110, 230 V/2.2 kVA	
Pressured air	6 bar	

### Options

Observation and Inspection Video, RW1, RW2
Split Field Optics, Mirage, RV1
Solder Removal Module, RC4
Reballing Module, RC5
Solder Paste Printing Heads, RC1
Board Temperature Sensor ... Tt, Gas Switching ... GS
Proven soldering head technology

[www.finetech.de](http://www.finetech.de)

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